

SOT945-1

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 5 x 5 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40R
Package type industry code	HVQFN40R
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.95	-	5	5.05	mm
E	package width	4.95	-	5	5.05	mm
A	seated height	[tbd]	-	0.8	0.85	mm
A ₂	package height	[tbd]	-	0.8	[tbd]	mm
n ₂	actual quantity of termination	-	-	40	-	

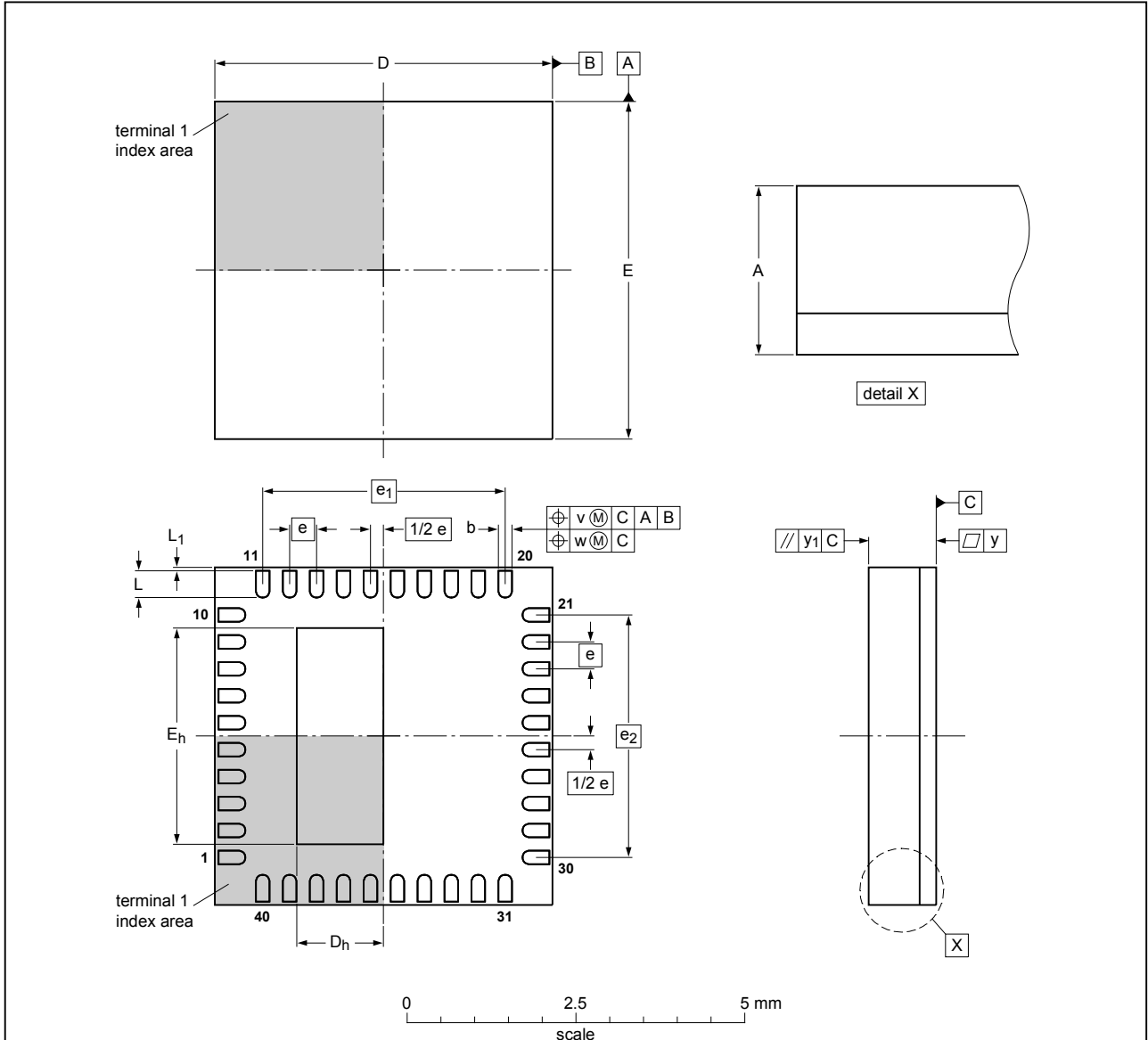


plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 5 x 5 x 0.8 mm

2. Package outline

HVQFN40R: plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; resin based; body 5 x 5 x 0.8 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	0.85	0.22 0.18	5.05 4.95	1.4 1.2	5.05 4.95	3.3 3.1	0.4	3.6	3.6	0.42 0.38	0.1 0	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT945-1	---	---	---			07-01-22 07-11-14

Fig. 1. Package outline HVQFN40R (SOT945-1)

plastic thermal enhanced very thin quad flat
package; no leads; 40 terminals; body 5 x 5 x 0.8
mm

3. Legal information

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